



<b>Title of Change:</b>	Qualification of Etching lead frame with 8008HT epoxy for X2DFN2 Device NSR0240MXT5G at ON Semiconductor, Leshan, China facility.		
<b>Proposed first ship date:</b>	17 September 2016		
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Harry.Tian@onsemi.com>		
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <Harry.Tian@onsemi.com>		
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or ZZ Cheng<S1016z@onsemi.com>.		
<b>Type of notification:</b>	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact &lt;PCN.Support@onsemi.com&gt;.</p>		
<b>Change Part Identification:</b>	<p>Upon the expiration of this FPCN, device (NSR0240MXT5G) will be assembled with Etching lead frame and 8008HT epoxy at ON Semiconductor's existing Leshan facility.</p> <p>Products assembled with Etching lead frame and 8008HT epoxy from the ON Semiconductor facility will have a Finish Goods Date Code of WW37, 2016 or greater.</p>		
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
<b>Change Sub-Category(s):</b>		<input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change		<input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Product specific change	
<b>Sites Affected:</b> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Leshan, China <input type="checkbox"/> External Foundry/Subcon site(s)			
<b>Description and Purpose:</b>  <p>ON Semiconductor is notifying customer of its use of Etching lead frame with 8008HT epoxy for NSR0240MXT5G at ON Semiconductor's Leshan, China facility.</p> <p>At the expiration of this PCN, these devices will be built with Etching lead frame and 8008HT epoxy at the same site. Datasheet specifications and product electrical performance remain unchanged. Reliability Qualification and full electrical characterization over temperature has been performed.</p>			

**Reliability Data Summary:****NSR0240MXT5G**

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Temp = -65°C to +150°C; for 1000 cycles (JA104B)	1000 Cycle	0/252
HTRB	JESD22-A108	Tj=150C or operating Tj 80% V bias (JA108)	1008 Hrs	0/252
H3TRB	J-STD-020 JA113	Temp = +85°C; RH = 85%, 80% V bias (JA101)	1008 Hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, deltaTj=100°C max, 2min on/off for 15000 cyc	15000 Cycle	0/252
UHASt	JESD22-A118	Temp = +130°C; RH = 85%, psig ~28 (JA118)	96 Hrs	0/252

**Electrical Characteristic Summary:**

Three temperature characterization and ESD performance meet datasheet specification. Detail of Electrical characterization result is available upon request.

**List of affected Standard Parts:**

Part Number	Qualification Vehicle
NSR0240MXT5G	NSR0240MXT5G